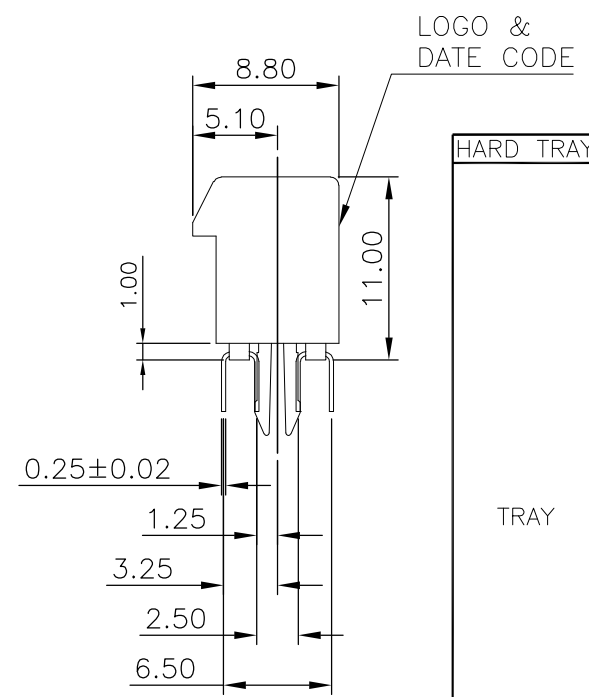
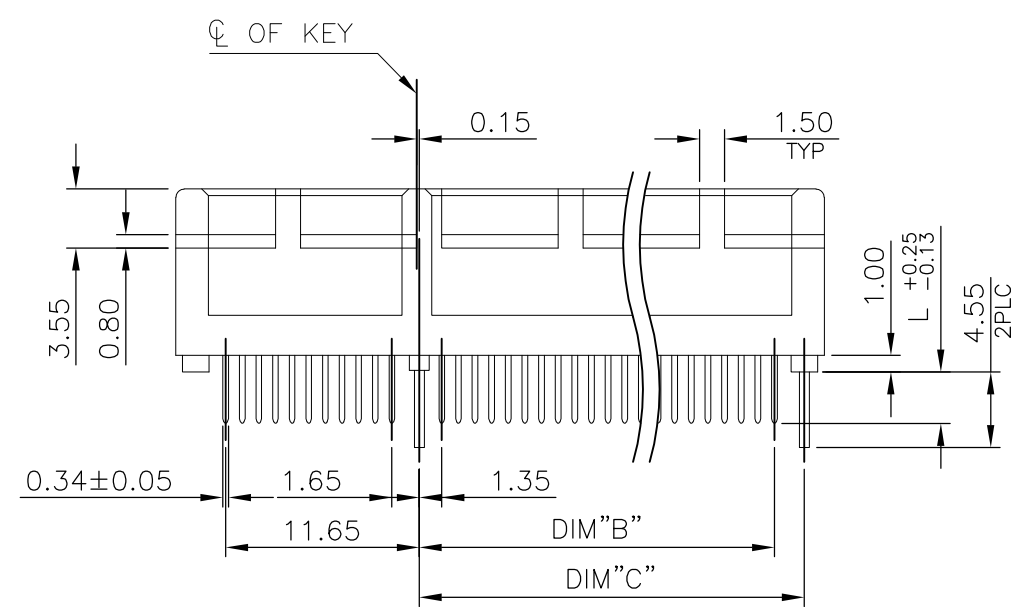
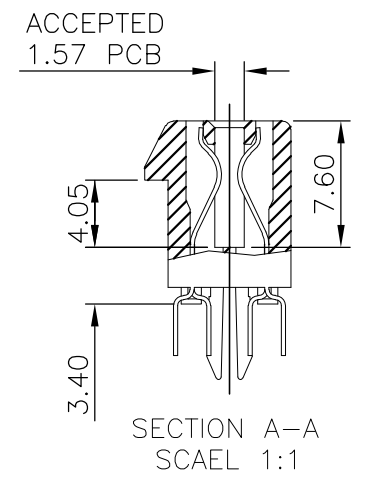
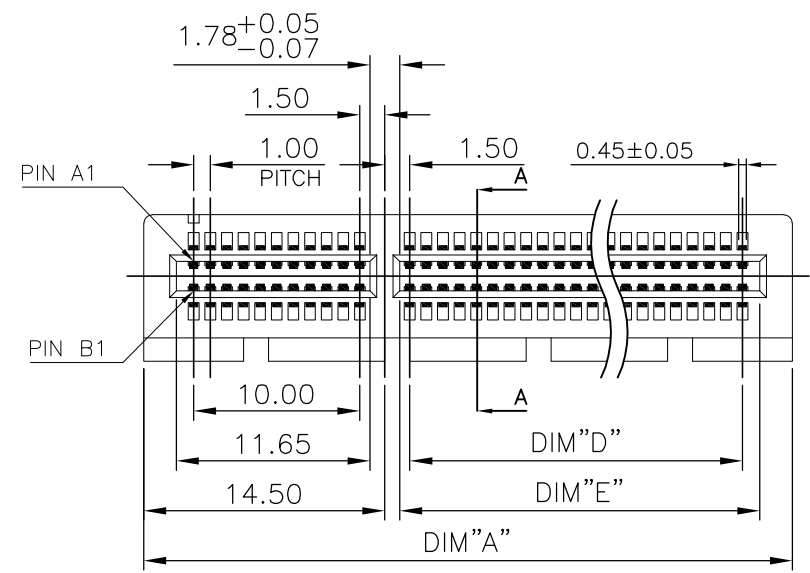


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REVISIONS					
P	LTR	DESCRIPTION	DATE	DWN	APVD
D		ECR-16-014363	11OCT2016	FL	SY

- NOTE:
- MATERIAL:
 HOUSING (SEE TABLE): PA46 OR PA9T, UL94 V-0, COLOR: BLACK.
 CONTACTS: PHOSPHOR BRONZE.
 BOARDLOCK: BRASS.
 - FINISH:
 2.1 CONTACTS: (SEE TABLE) GOLD PLATED ON CONTACT AREA, 2.54um [100u"] MIN. MATTE-TIN ON SOLDER TAIL, WITH ENTIRE CONTACT UNDERPLATED 1.27um [50u"] MIN. NICKEL.
 2.2 BOARDLOCK: 2.54um [100u"] MATTE-TIN PLATING ALL OVER NICKEL 1.27um[50u"] MIN. UNDERPLATED OVERALL.
 - WAVE SOLDER CAPABLE TO 265°C MAX. PER TE SPEC. 109-202, CONDITION B.
 - WEIGHT:
 36 POS.: 2.55 GRAMS
 64 POS.: 3.90 GRAMS
 98 POS.: 5.50 GRAMS
 164 POS.: 8.80 GRAMS
 - REFLOW SOLDER CAPABLE TO 260°C PER TE SPEC. TEC-109-201, CONDITION B.

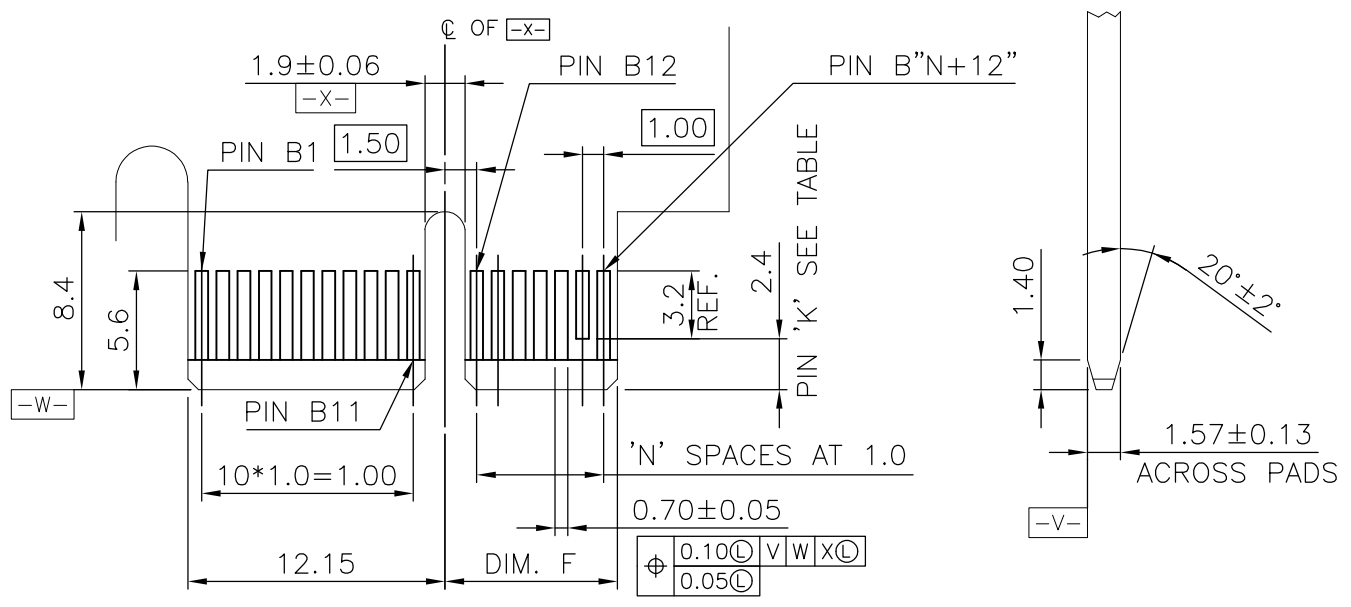


TRAY	NOTE	PA9T	2.30	0.381µm[15µ"] MIN.	71.65	70.0	73.15	71.35	89.0	164	6-	-2
HARD TRAY	NOTE 3 & 5	PA9T	3.10	0.762µm[30µ"] MIN.	71.65	70.0	73.15	71.35	89.0	164	5-	-2
				0.381µm[15µ"] MIN.							4-	-6
			2.30	GOLD FLASH	71.65	70.0	73.15	71.35	89.0	164	4-	-5
				0.762µm[30µ"] MIN.							4-	-4
			3.10	0.381µm[15µ"] MIN.	38.65	37.0	40.15	38.35	56.0	98	4-	-3
				GOLD FLASH							4-	-2
			2.30	0.762µm[30µ"] MIN.	38.65	37.0	40.15	38.35	56.0	98	4-	-1
				0.381µm[15µ"] MIN.							3-	-6
			3.10	GOLD FLASH	21.65	20.0	23.15	21.35	39.0	64	3-	-5
				0.762µm[30µ"] MIN.							3-	-4
			2.30	0.381µm[15µ"] MIN.	21.65	20.0	23.15	21.35	39.0	64	3-	-3
				GOLD FLASH							2-	-5
3.10	0.762µm[30µ"] MIN.	7.65	6.0	9.15	7.35	25.0	36	2-	-4			
	0.381µm[15µ"] MIN.							2-	-3			
2.30	GOLD FLASH	7.65	6.0	9.15	7.35	25.0	36	2-	-2			
	0.762µm[30µ"] MIN.							1-	-6			
3.10	0.381µm[15µ"] MIN.	7.65	6.0	9.15	7.35	25.0	36	1-	-5			
	GOLD FLASH							1-	-4			
2.30	0.762µm[30µ"] MIN.	7.65	6.0	9.15	7.35	25.0	36	1-	-3			
	0.381µm[15µ"] MIN.							1-	-2			
3.10	GOLD FLASH	7.65	6.0	9.15	7.35	25.0	36	1-	-1			
	0.762µm[30µ"] MIN.							1-	-2			
2.30	0.381µm[15µ"] MIN.	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	GOLD FLASH							1-	-2			
3.10	0.762µm[30µ"] MIN.	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	0.381µm[15µ"] MIN.							1-	-2			
2.30	GOLD FLASH	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	0.762µm[30µ"] MIN.							1-	-2			
3.10	0.381µm[15µ"] MIN.	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	GOLD FLASH							1-	-2			
2.30	0.762µm[30µ"] MIN.	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	0.381µm[15µ"] MIN.							1-	-2			
3.10	GOLD FLASH	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	0.762µm[30µ"] MIN.							1-	-2			
2.30	0.381µm[15µ"] MIN.	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	GOLD FLASH							1-	-2			
3.10	0.762µm[30µ"] MIN.	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	0.381µm[15µ"] MIN.							1-	-2			
2.30	GOLD FLASH	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	0.762µm[30µ"] MIN.							1-	-2			
3.10	0.381µm[15µ"] MIN.	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	GOLD FLASH							1-	-2			
2.30	0.762µm[30µ"] MIN.	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	0.381µm[15µ"] MIN.							1-	-2			
3.10	GOLD FLASH	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	0.762µm[30µ"] MIN.							1-	-2			
2.30	0.381µm[15µ"] MIN.	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	GOLD FLASH							1-	-2			
3.10	0.762µm[30µ"] MIN.	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	0.381µm[15µ"] MIN.							1-	-2			
2.30	GOLD FLASH	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	0.762µm[30µ"] MIN.							1-	-2			
3.10	0.381µm[15µ"] MIN.	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	GOLD FLASH							1-	-2			
2.30	0.762µm[30µ"] MIN.	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	0.381µm[15µ"] MIN.							1-	-2			
3.10	GOLD FLASH	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	0.762µm[30µ"] MIN.							1-	-2			
2.30	0.381µm[15µ"] MIN.	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	GOLD FLASH							1-	-2			
3.10	0.762µm[30µ"] MIN.	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	0.381µm[15µ"] MIN.							1-	-2			
2.30	GOLD FLASH	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	0.762µm[30µ"] MIN.							1-	-2			
3.10	0.381µm[15µ"] MIN.	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	GOLD FLASH							1-	-2			
2.30	0.762µm[30µ"] MIN.	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	0.381µm[15µ"] MIN.							1-	-2			
3.10	GOLD FLASH	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	0.762µm[30µ"] MIN.							1-	-2			
2.30	0.381µm[15µ"] MIN.	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	GOLD FLASH							1-	-2			
3.10	0.762µm[30µ"] MIN.	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	0.381µm[15µ"] MIN.							1-	-2			
2.30	GOLD FLASH	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	0.762µm[30µ"] MIN.							1-	-2			
3.10	0.381µm[15µ"] MIN.	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	GOLD FLASH							1-	-2			
2.30	0.762µm[30µ"] MIN.	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	0.381µm[15µ"] MIN.							1-	-2			
3.10	GOLD FLASH	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	0.762µm[30µ"] MIN.							1-	-2			
2.30	0.381µm[15µ"] MIN.	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	GOLD FLASH							1-	-2			
3.10	0.762µm[30µ"] MIN.	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
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	0.762µm[30µ"] MIN.							1-	-2			
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	GOLD FLASH							1-	-2			
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	0.381µm[15µ"] MIN.							1-	-2			
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2.30	0.381µm[15µ"] MIN.	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	GOLD FLASH							1-	-2			
3.10	0.762µm[30µ"] MIN.	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	0.381µm[15µ"] MIN.							1-	-2			
2.30	GOLD FLASH	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	0.762µm[30µ"] MIN.							1-	-2			
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	GOLD FLASH							1-	-2			
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	GOLD FLASH							1-	-2			
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	GOLD FLASH							1-	-2			
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	0.762µm[30µ"] MIN.							1-	-2			
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	GOLD FLASH							1-	-2			
3.10	0.762µm[30µ"] MIN.	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
	0.381µm[15µ"] MIN.							1-	-2			
2.30	GOLD FLASH	7.65	6.0	9.15	7.35	25.0	36	1-	-2			
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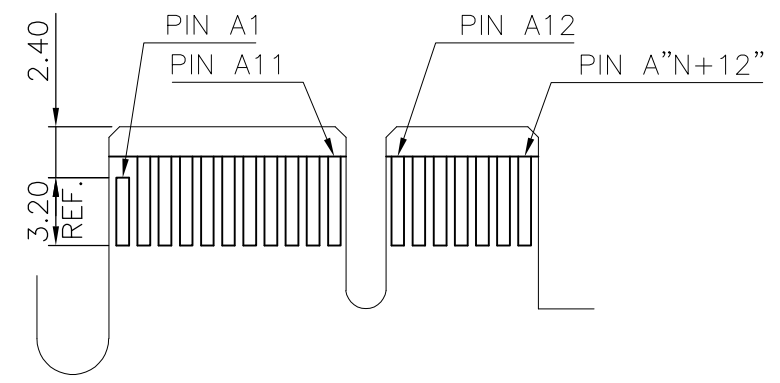
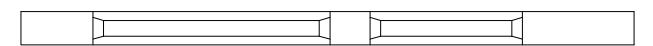
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REVISIONS					
P	LTR	DESCRIPTION	DATE	DWN	APVD
-	-	SEE SHEET 1	-	-	-

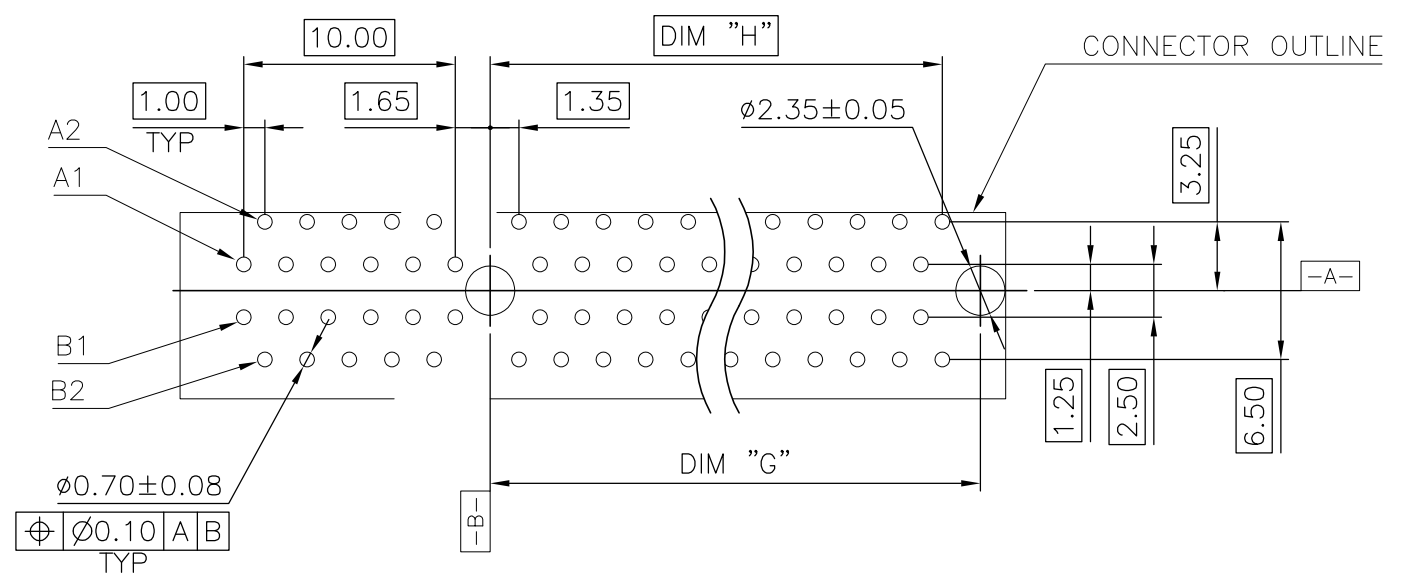
1. NO TIE BAR PERMITTED FROM CARD EDGE TO LEADING EDGE OF PAD FOR PINS A1 AND "K"
2. CHAMFER EDGE MUST BE FREE OF CUTTING BURRS



I/O PANEL DIRECTION
 PRIMARY (COMPONENT) SIDE



SECONDARY (SOLDER) SIDE



RECOMMENDED PCB LAYOUT

TOLERANCE: ±0.05
 DIM.L=3.1mm THICKNESS: 2.4mm
 DIM.L=2.3mm THICKNESS: 1.6mm

POS.	N	DIM. F	DIM. G	DIM. H	"K"
36	6	8.15	9.15	7.35	B17
64	20	22.15	23.15	21.35	B17,B31
98	37	39.15	40.15	38.35	B17,B31,B48
164	70	72.15	73.15	71.35	B17,B31,B48,B81

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN B. HSING 21MAY2009	TE Connectivity														
DIMENSIONS: mm		CHK S. CHIEN 21MAY2009															
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD W. KODAMA 21MAY2009	NAME														
<table border="0"> <tr><td>0 PLC</td><td>± -</td></tr> <tr><td>1 PLC</td><td>± 0.3</td></tr> <tr><td>2 PLC</td><td>± 0.2</td></tr> <tr><td>3 PLC</td><td>± 0.15</td></tr> <tr><td>4 PLC</td><td>± -</td></tr> <tr><td>ANGLES</td><td>± 3°</td></tr> </table>		0 PLC	± -	1 PLC	± 0.3	2 PLC	± 0.2	3 PLC	± 0.15	4 PLC	± -	ANGLES	± 3°	PRODUCT SPEC	PCI EXPRESS CARD EDGE CONNECTOR VERTICAL, DIP TYPE,(BOARD-LOCK FUNCTION)		
0 PLC	± -																
1 PLC	± 0.3																
2 PLC	± 0.2																
3 PLC	± 0.15																
4 PLC	± -																
ANGLES	± 3°																
MATERIAL		APPLICATION SPEC	SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO											
-		FINISH	-	-	A300779	C-1775801											
CUSTOMER DRAWING			WEIGHT	0	SCALE 1:1 SHEET 2 OF 4 REV D												

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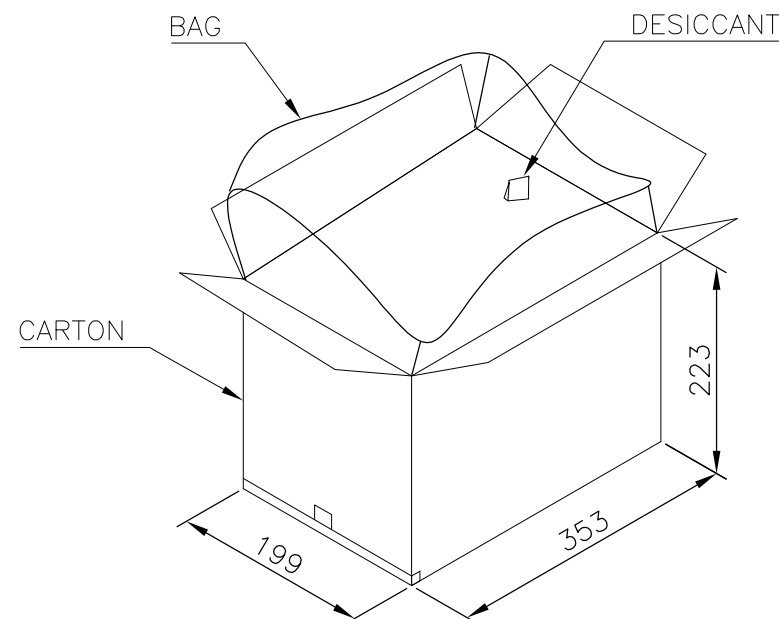
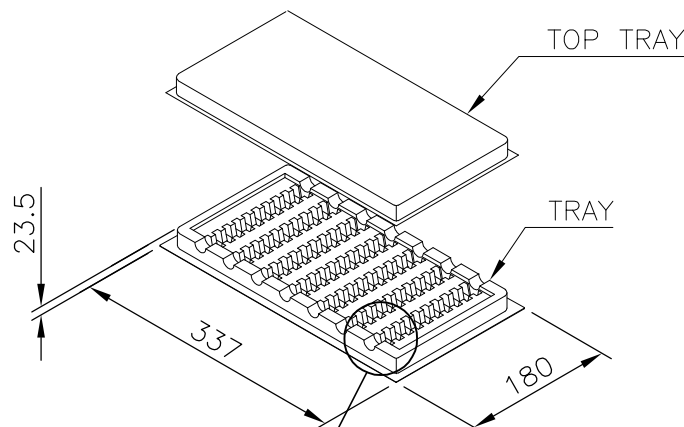
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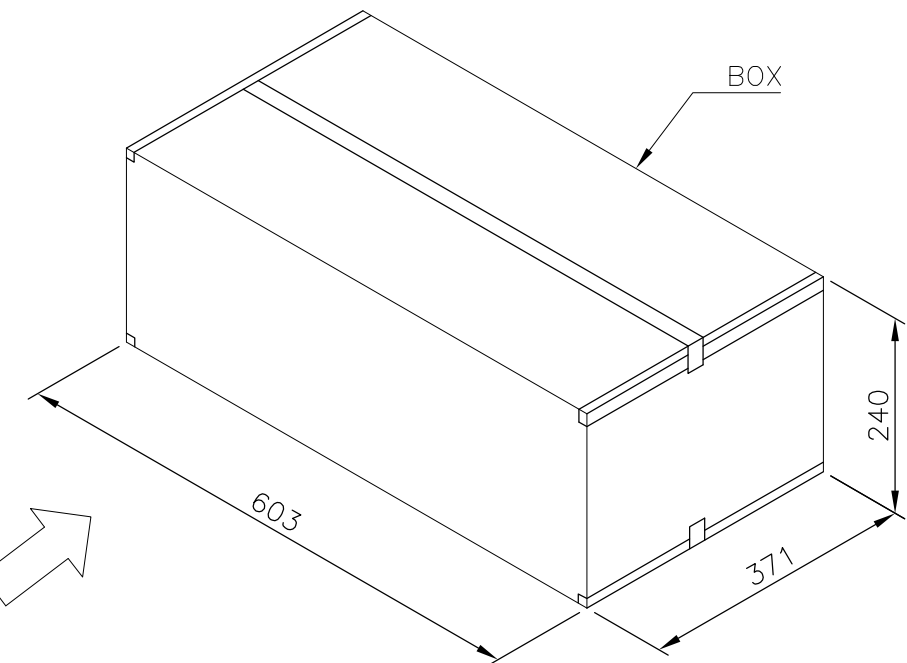
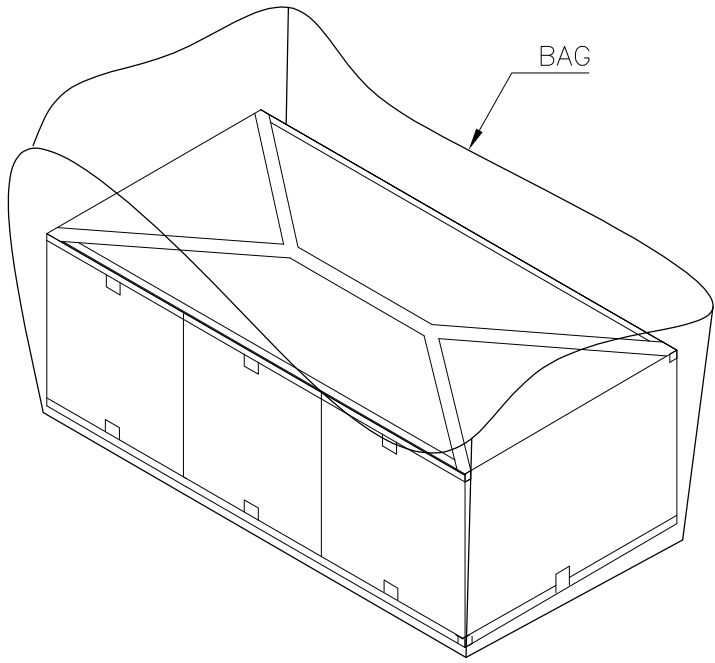
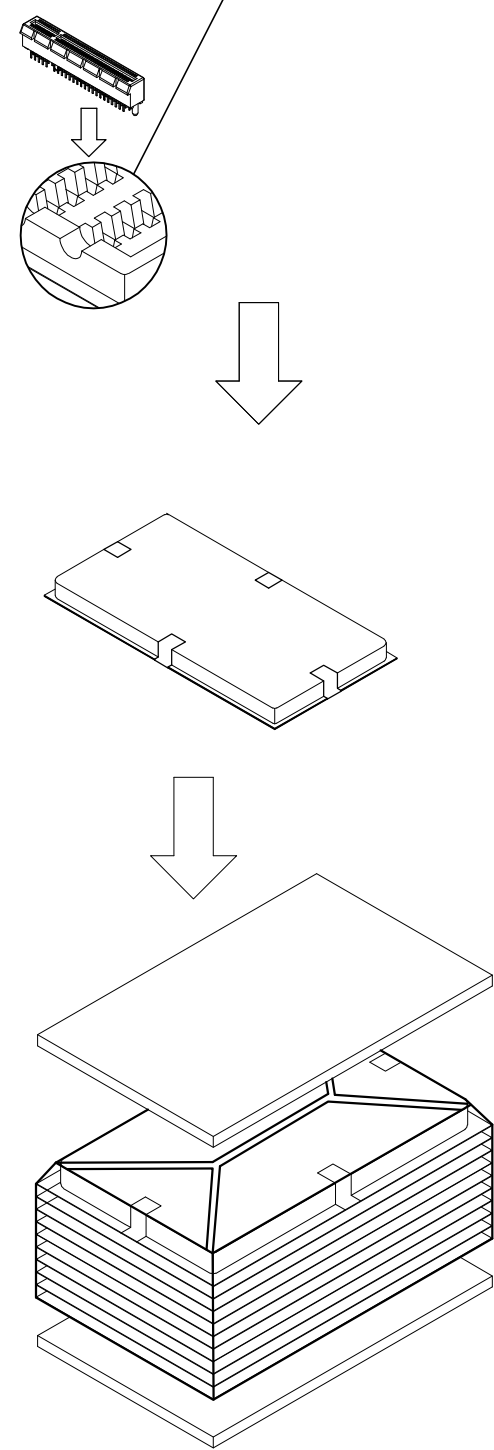
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REVISIONS

P	LTR	DESCRIPTION	DATE	DWN	APVD
-	-	SEE SHEET 1	-	-	-



- NOTES :
- MATERIAL :
TRAY : PVC, COLOR: TRANSPARENT.
CARTON: CORRUGATED FIBER
BOX: CORRUGATED FIBER
 - DIMENSION :
TRAY: SEE DRAWING
CARTON: SEE DRAWING
BOX : SEE DRAWING
 - QUANTITY : SEE TABLE
 - WEIGHT : SEE TABLE



9.6 KG	7.6 KG	30	10	3	900	164
8.5 KG	6.5 KG	40	10	3	1200	98
9.1 KG	7.1 KG	60	10	3	1800	64
7.7 KG	5.7 KG	70	10	3	2100	36
GROSS WEIGHT	NET WEIGHT	PCS/ TRAY	TRAY/ CARTON	CARTON/ BOX	PCS/ BOX	POS

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS:	TOLERANCES UNLESS OTHERWISE SPECIFIED:
mm	
	0 PLC ± -
	1 PLC ± -
	2 PLC ± -
	3 PLC ± -
	4 PLC ± -
	ANGLES ± -
MATERIAL	FINISH
-	-

DWN	B. HSING	21MAY2009
CHK	S. CHIEN	21MAY2009
APVD	W. KODAMA	21MAY2009
PRODUCT SPEC	-	
APPLICATION SPEC	-	
WEIGHT	0	



PCI EXPRESS CARD EDGE CONNECTOR VERTICAL, DIP TYPE,(BOARD-LOCK FUNCTION)

SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO
A3	00779	C-1775801	-
CUSTOMER DRAWING		SCALE 1:1	SHEET 3 OF 4 REV D

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REVISIONS

P	LTR	DESCRIPTION	DATE	DWN	APVD
-	-	SEE SHEET 1	-	-	-

NOTES :

PACKING MATERIAL MET TE SPEC TEC-138-702.

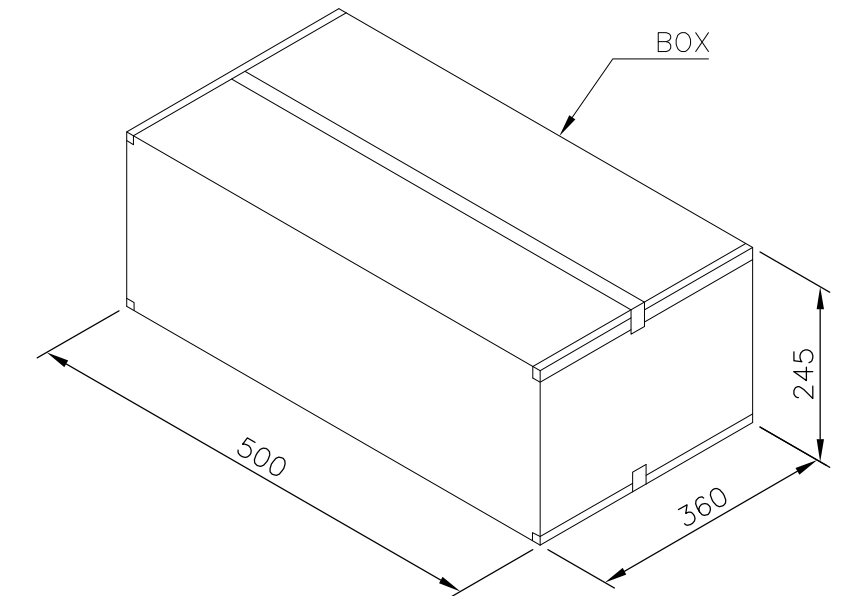
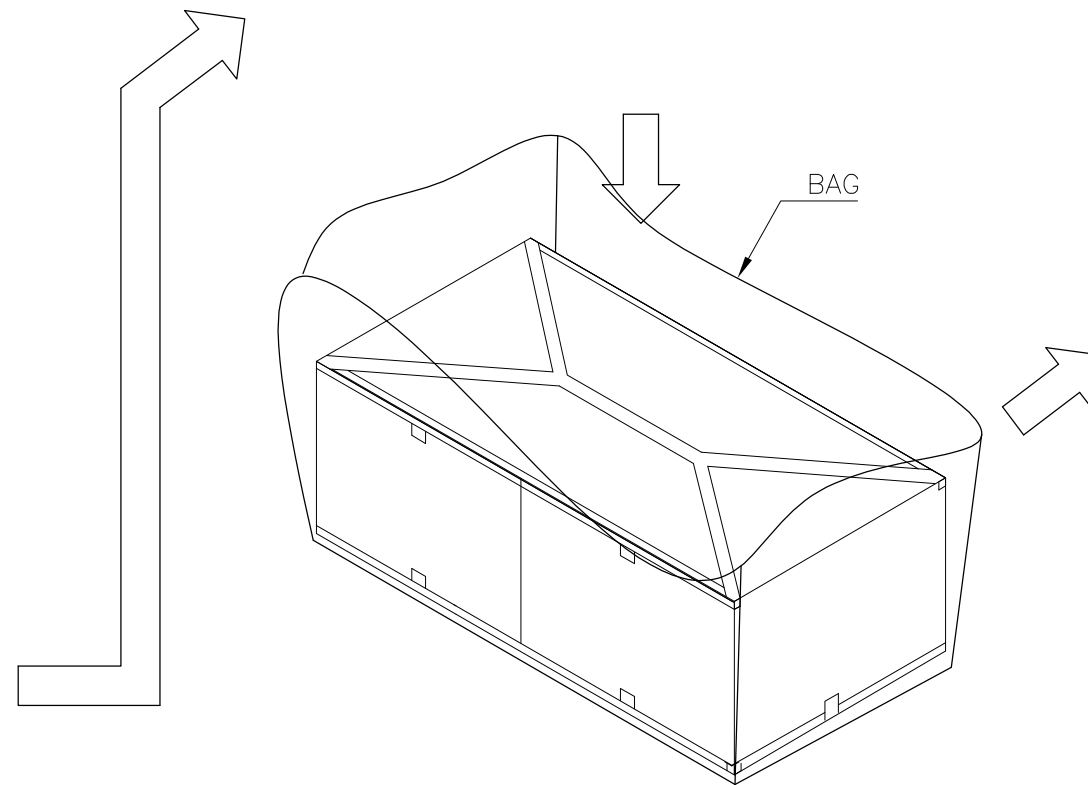
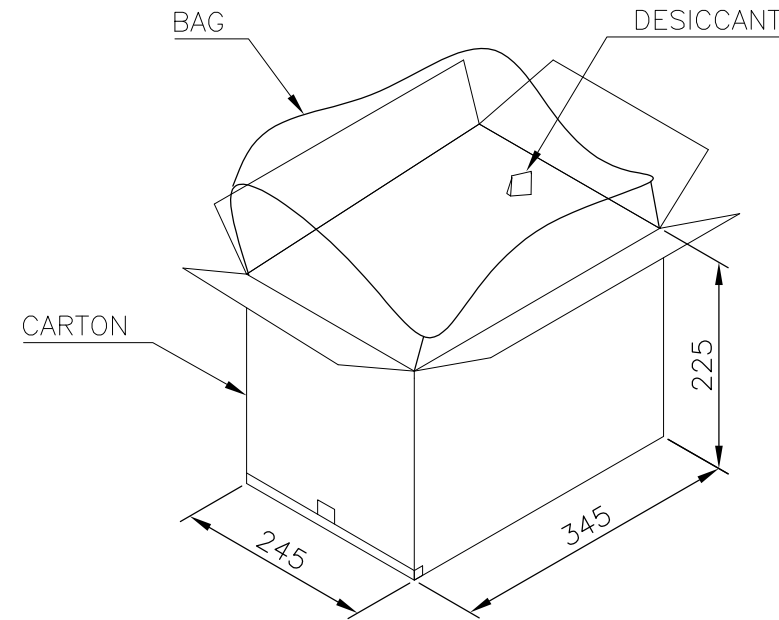
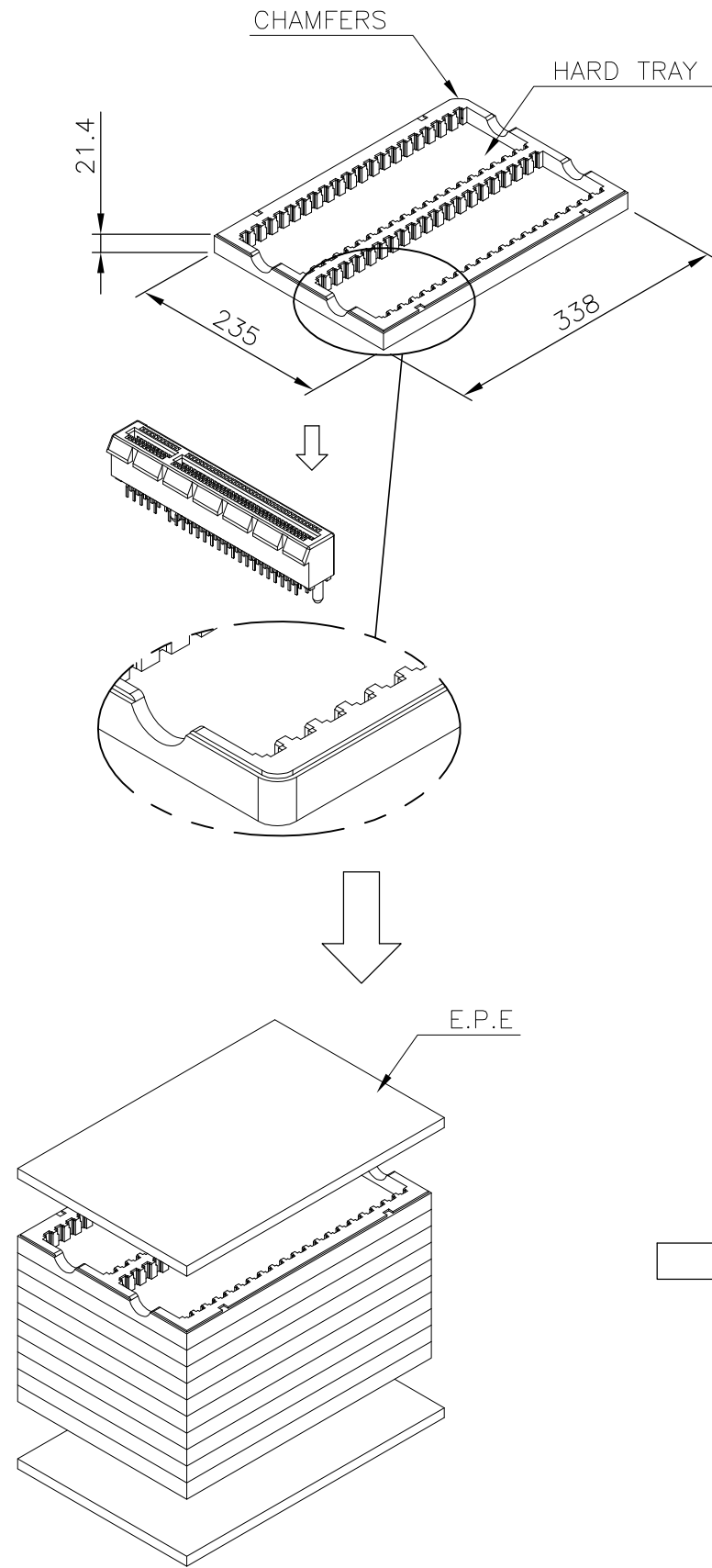
- * CADMIUM AND CADMIUM COMPOUNDS CONTENT:
5 PPM UNDER (PLASTIC, RUBBER, INK, PIGMENT, PAINT)
- * LEAD, CADMIUM, CHROM VI AND MERCURY IN PACKAGING MATERIALS CONTENT: 100 PPM (COMBINED) UNDER.

1. MATERIAL :

TRAY: HIPS, COLOR: BLACK.
 CARTON: CORRUGATED FIBER
 BOX: CORRUGATED FIBER
 TRANSPARENT BAG: PE, SIZE: 500mm*380mm*0.06mm
 640mm*510mm*0.06mm

2. EACH BAG SHALL BE INCLUDED:

- * DESICCANT



11.5 Kg	7.0 Kg	40	10	2	800	164
GROSS WEIGHT	NET WEIGHT	PCS/ TRAY	TRAY/ CARTON	CARTON/ BOX	PCS/ BOX	POS

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS:		TOLERANCES UNLESS OTHERWISE SPECIFIED:	
mm			
	0 PLC	±	-
	1 PLC	±	-
	2 PLC	±	-
	3 PLC	±	-
	4 PLC	±	-
	ANGLES	±	-
MATERIAL		FINISH	
-		-	

DWN	B. HSING	21MAY2009
CHK	S. CHIEN	21MAY2009
APVD	W. KODAMA	21MAY2009
PRODUCT SPEC	-	
APPLICATION SPEC	-	
WEIGHT	0	
CUSTOMER DRAWING		

				TE Connectivity		
PCI EXPRESS CARD EDGE CONNECTOR VERTICAL, DIP TYPE,(BOARD-LOCK FUNCTION)						
SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO			
A3	00779	C-1775801	-			
SCALE			SHEET		REV	
1:1			4 OF 4		D	

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9